CLAIMS

1. A method for manufacturing an electronic device, comprising at least:

a step (1) of preparing a structure having:

an adhesive film having:

a base material layer;

an adhesive resin layer (A) for temporarily fixing an electronic component, which is provided on a first surface side of the base material layer; and

an adhesive resin layer (B) in which an adhesive force is decreased by an external stimulus, which is provided on a second surface side of the base material layer;

an electronic component attached to the adhesive resin layer (A) of the adhesive film; and

a support substrate attached to the adhesive resin layer (B) of the adhesive film;

a step (2-2) of decreasing water content in the structure; and

a step (3) of sealing the electronic component with a sealing material, and

wherein the step (2-2) is performed between the step (~~2~~1) and the step (3).

2. A method for manufacturing an electronic device, comprising at least:

a step (1) of preparing a structure having:

an adhesive film having:

a base material layer;

an adhesive resin layer (A) for temporarily fixing an electronic component, which is provided on a first surface side of the base material layer; and

an adhesive resin layer (B) in which an adhesive force is decreased by an external stimulus, which is provided on a second surface side of the base material

layer;

an electronic component attached to the adhesive resin layer (A) of the adhesive film; and

a support substrate attached to the adhesive resin layer (B) of the adhesive film;

at least one step (2) selected from a step (2-1) of decreasing water content in the adhesive film and a step (2-2) of decreasing water content in the structure; and

a step (3) of sealing the electronic component with a sealing material, and

wherein an interval between the step (2) and the step (3) is within 12 hours.

3. The method for manufacturing an electronic device according to claim 2,

wherein the step (2) includes the step (2-1) of decreasing the water content in the adhesive film, and

the step (2-1) is performed before the step (1).

4. The method for manufacturing an electronic device according to claim 3,

wherein, in the step (2-1), the water content in the adhesive film is decreased by heating the adhesive film and/or depressurizing the adhesive film.

5. The method for manufacturing an electronic device according to claim 2,

wherein the step (2) includes the step (2-2) of decreasing the water content in the structure, and

the step (2-2) is performed between the step (1) and the step (3).

6. The method for manufacturing an electronic device according to claim 1 or 5,

wherein, in the step (2-2), the water content in the structure is decreased by heating the structure and/or

depressurizing the structure.

7. The method for manufacturing an electronic device according to claim 5 or 6,

wherein the step (2-2) is performed immediately before the step (3).

8. The method for manufacturing an electronic device according to any one of claims 1 to 7, further comprising:

a step (4) of peeling the support substrate from the structure by decreasing an adhesive force of the adhesive resin layer (B) by applying an external stimulus, after the step (3).

9. The method for manufacturing an electronic device according to claim 8, further comprising:

a step (5) of peeling the adhesive film from the electronic component, after the step (4).

10. The method for manufacturing an electronic device according to any one of claims 1 to 9,

wherein the sealing material is an epoxy resin-based sealing material.

11. The method for manufacturing an electronic device according to any one of claims 1 to 10,

wherein the adhesive resin layer (A) includes a (meth)acrylic adhesive resin.